

Thermal Interface Material



KL 95



- Highly ceramic filled adhesive tape.

Applications

- CPU, LEDs
- Power Supplies and inverter modules
- Telecommunication electronics
- Automotive electronics
- MOSFET on heat sinks
- Flip Chips, DSPs
- BGAs, PPGAs on heat sinks

Options

- KL95 has a shelf life of 12 months after day of manufacture

Properties	Unit	KL 95
Color		Grey
Thermal Properties		
Thermal Conductivity	W/mK	1.3
Thermal Resistance	K/W	0.32
Electrical Properties		
Breakdown Voltage $U_{d; ac}$	kV	2
Dielectric Breakdown $E_{d; ac}$	kV/mm	10
Volume Resistivity	Ωm	$2.0 * 10^{11}$
Dielectric Constant	(1KHz)	1.7
Dielectric Loss Factor $\tan\delta$	(1KHz)	$2.4 * 10^{-1}$
Mechanical Properties		
Hardness	Shore A	60
Tensile shear strength	N/cm ²	>6.5
Physical Properties		
Application Temperature	°C (°F)	-40 to +100 (-40 to +212)
Density	g/cm ³	2.24
Adhesion(bonding strength)	Nmm	>0.5
Tack(surface adhesiveness)	mm	>1.0
Possible Thickness	mm (inch)	0.18-0.3(0.007-0.012)

The data provide engineering guidance, performance in actual applications should be established through testing.